

**Listing of Claims:**

1-28. (canceled)

29. (new) An apparatus for transferring heat from semiconductive devices during a burn-in operation, comprising:

- a. a base board;
- b. a plurality of openings extending through the base board for inspecting and repairing a semiconductor device;
- c. heat sinks coordinated with the openings, each having a contact surface for engaging a semiconductor device positioned in a socket of a burn-in board;  
and
- d. biasing members having two ends; one end mounted on the base board and the other end connected to a heat sink for urging the contact surface of the heat sink against a semiconductor device.

30. (new) The apparatus of claim 29, in which the base board is further attached to the burn-in board having a plurality of sockets for semiconductive devices, and the sinks are positioned between the base board and the burn-in board.

31. (new) The apparatus of claim 29, in which the heat sinks include upstanding fins.

32. (new) The apparatus of claim 30, in which the openings provide access for measuring semiconductive devices in the sockets.

33. (new) The apparatus of claim 30, further comprising, between the base board and the burn-in board, a path for laminar airflow around the semiconductive devices in the sockets.

34. (new) The apparatus of claim 29, in which the biasing member further comprises a stabilization member retractably extending through the base board for limiting the movement of the heat sink laterally.

35. (new) A method for burn-in semiconductor devices; comprising
- a. providing a burn-in board with a plurality of sockets;
  - b. populating the sockets with semiconductor devices under burn-in;
  - c. attaching to the burn-in board an apparatus, which includes:
    - i. a base board;
    - ii. a plurality of openings extending through the base board for inspecting and repairing a semiconductor device;
    - iii. heat sinks coordinated with the openings, each having a contact surface for engaging a semiconductor device positioned in a socket of a burn-in board; and
    - iv. biasing members having two ends; one end mounted on the base board and the other end connected to a heat sink for urging the contact surface of the heat sink against a semiconductor device;
  - d. raising the temperature near the sockets to a desirable degree;
  - e. engaging the heat sinks to the semiconductor devices to maintain the devices at a desirable temperature; and
  - f. burning-in the semiconductor devices.
36. (new) The method of claim 35, further comprising providing laminate airflow between the base board and the burn-in board and directing the airflow to the vicinity of the semiconductor devices to maintain a desirable device temperature.
37. (new) The method of claim 35, further comprising the steps of inspecting the semiconductors via the openings on the base board.
38. (new) The method of claim 35, further comprising the steps of repairing the semiconductors via the openings on the base board.
- 39 (new) The method of claim 35, further comprising the steps of measuring the semiconductors via the openings on the base board.